L Number	Hits	Search Text	DB	Time stamp
1	824	425/123.ccls. 425/89.ccls.	USPAT	2003/09/24
2	325	425/125.ccls.	USPAT	2003/09/24
3	291	425/125.ccls. not (425/123.ccls. 425/89.ccls.)	USPAT	2003/09/24
4	199	425/121.ccls.	USPAT	2003/09/24
5	156	425/121.ccls. not (425/125.ccls. (425/123.ccls. 425/89.ccls.)	USPAT	2003/09/24
6	212	425/544.ccls.	USPAT	2003/09/24
7	168	425/544.ccls. not (425/121.ccls. (425/123.ccls. 425/89.ccls.) 425/125.ccls.)	USPAT	2003/09/24
8	852	425/577.ccls.	USPAT	2003/09/24
9	809	425/577.ccls. not (425/544.ccls. 425/121.ccls. (425/123.ccls.	USPAT	2003/09/24
10	11	425/89.ccls.)	USPAT	2003/09/24 13:39
11	4	("3136831" "3587156" "3608046" "4187272").PN.	USPAT	2003/09/24
12	5	4298566.URPN.	USPAT	2003/09/24
13	807	425/129.1.ccls.	USPAT	2003/09/24
14	546	425/129.1.ccls. not (425/577.ccls. 425/544.ccls. (425/123.ccls. 425/89.ccls.) 425/121.ccls. 425/125.ccls.)	USPAT	2003/09/24
15	4	("4244491" "4893725" "5049336" "5395005").PN.	USPAT	2003/09/24
16	524	425/127.ccls.	USPAT	2003/09/24 14:22
17	281	425/127.ccls. not (425/129.1.ccls. 425/577.ccls. 425/544.ccls. (425/123.ccls. 425/89.ccls.) 425/121.ccls. 425/125.ccls.)	USPAT	2003/09/24
18	595	l '	USPAT	2003/09/24
19	176	264/272.14.ccls.	USPAT	2003/09/24
20	150	264/272.14.ccls. not (425/127.ccls. 425/129.1.ccls. 425/577.ccls. 425/544.ccls. (425/123.ccls. 425/89.ccls.) 425/121.ccls. 425/125.ccls.)	USPAT	2003/09/24 14:33
21	563	264/316.ccls. not (264/272.14.ccls. 425/127.ccls. 425/129.1.ccls. 425/577.ccls. 425/544.ccls. (425/123.ccls. 425/89.ccls.) 425/121.ccls. 425/125.ccls.)	USPAT	2003/09/24 14:33
22	346573	semiconductor (semi adj conductor) encapsulation encapsulating encapsulate	USPAT	2003/09/24
23	5	(264/316.ccls. not (264/272.14.ccls. 425/127.ccls. 425/129.1.ccls. 425/577.ccls. 425/544.ccls. (425/123.ccls. 425/89.ccls.) 425/121.ccls. 425/125.ccls.)) and	USPAT	2003/09/24 14:34
		(semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)		

24		558	(264/316.ccls. not (264/272.14.ccls.	USPAT	2003/09/24
1			425/127.ccls. 425/129.1.ccls.		14:40
1			425/577.ccls. 425/544.ccls.		
1			(425/123.ccls. 425/89.ccls.) (425/121.ccls. 425/125.ccls.)) not		
1			((264/316.ccls. not (264/272.14.ccls.	}	Į.
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1			425/121.ccls. 425/125.ccls.)) and		<u>.</u>
-			(semiconductor (semi adj conductor)		
1			encapsulation encapsulating encapsulate))		
25		692	264/272.17.ccls.	USPAT	2003/09/24
				}	14:40
26		488	264/272.17.ccls. not ((264/316.ccls. not	USPAT	2003/09/24
1			(264/272.14.ccls. 425/127.ccls.		14:43
1		,	425/129.1.ccls. 425/577.ccls.		
1			425/544.ccls. (425/123.ccls.		
			425/89.ccls.) 425/121.ccls.	-	
1		!	425/125.ccls.)) ((264/316.ccls. not	}	
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			encapsulating encapsulate))		
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-			425/125.ccls.)		
27		34760	(release parting) near5 (film sheet	USPAT	2003/09/24
" '		34700	layer)	JULAI	14:46
28		21	(264/272.17.ccls. not ((264/316.ccls. not	USPAT	2003/09/24
			(264/272.14.ccls. 425/127.ccls.		14:41
1			425/129.1.ccls. 425/577.ccls.	ţ	
		l I	425/544.ccls. (425/123.ccls.		1
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1			425/125.ccls.)) ((264/316.ccls. not	1	-
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1	Î	!	425/125.ccls.)) and (semiconductor (semi	1	
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}			425/125.ccls.) and ((release parting)		
	.		near5 (film sheet layer))	1	
29	1	4276	264/272.17.ccls. ((264/316.ccls. not	USPAT	2003/09/24
2.5	}	-12/0	(264/272.14.ccls. (264/316.ccls. not	JULAI	14:43
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L			425/125.ccls.)	L	L

30	338	438/112.ccls.	USPAT	2003/09/24
30	330	450/112.0015.	OSFAI	14:43
31	305	438/112.ccls. not (264/272.17.ccls.	USPAT	2003/09/24
- -	1	((264/316.ccls. not (264/272.14.ccls.		14:43
· ·	1	425/127.ccls. 425/129.1.ccls.	Į.	1
<u> </u>	+	425/577.ccls. 425/544.ccls.	1	
1	1	(425/123.ccls. 425/89.ccls.)	1]
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({	encapsulation encapsulating encapsulate))	}	· .
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		425/89.ccls.) 425/121.ccls.	}	1
32	3809	425/125.ccls.)) ((264/272.17.ccls. not ((264/316.ccls.	USPAT	2003/09/24
32	3009	not (264/272.14.ccls. 425/127.ccls.	USPAL	14:44
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1	}	near5 (film sheet layer))) ((264/316.ccls. not (264/272.14.ccls.	1	
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L		425/125.ccls.)	<u> </u>	<u> </u>

33	333	438/112.ccls. not (((264/272.17.ccls. not	USPAT	2003/09/24
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	l	425/577.ccls. 425/544.ccls.	į .	}
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34	6	(438/112.ccls. not (((264/272.17.ccls.	USPAT	2003/09/24
		not ((264/316.ccls. not (264/272.14.ccls.		14:45
}	}	425/127.ccls. 425/129.1.ccls.		
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35	0	holl021/56	DERWENT	2003/09/24
] 33		11011021/30	DEKWENT	14:46
36	10315	H01L021/56	DESTRUCTION	
36	10312	NO1L021/56	DERWENT	2003/09/24
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37	18434	(release parting) near5 (film sheet	DERWENT	2003/09/24
* *		layer)		14:46
38	101	H01L021/56 and ((release parting) near5	DERWENT	2003/09/24
,		(film sheet layer))	1	14:46
39	1	2002-350925.NRAN.	DERWENT	2003/09/24
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[-	5504	miyajima	JPO;	2003/09/24
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1	1		DERWENT	09:28
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_	383	425/89.ccls.	USPAT	2003/09/24
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